

PATENT ASSIGNMENT

Electronic Version v1.1
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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
Diamond Innovations, Inc.	01/20/2011
RECEIVING PARTY DATA	
Name:	Ehwa Diamond Industiral Company, Ltd.
Street Address:	520-2 Wondong, Osansi
City:	Kyunggido
State/Country:	KOREA, DEMOCRATIC PEOPLE'S REPUBLIC OF
Postal Code:	447804
PROPERTY NUMBERS Total: 6	
Property Type	Number
Patent Number:	7082939
Patent Number:	7089924
Patent Number:	7096863
Patent Number:	7637257
Patent Number:	7814895
Application Number:	12630887
CORRESPONDENCE DATA	
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<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>	
Phone:	614-438-2834
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Correspondent Name:	Maria C. Gasaway - Diamond Innovations
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Address Line 4:	Worthington, OHIO 43085
ATTORNEY DOCKET NUMBER:	EHWA IP TRANSFER

OP \$240.00 7082939

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PATENT
REEL: 026067 FRAME: 0020

NAME OF SUBMITTER:

Maria C. Gasaway

Total Attachments: 6

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PATENT ASSIGNMENT AGREEMENT

THIS PATENT ASSIGNMENT AGREEMENT ("Agreement") is made and entered into on this 20 day of January, 2011 by and between Diamond Innovations Inc., a company organized and existing under the laws of the state of Delaware in the United States of America, having its principal place of business at 6325 Huntley Road, Worthington, Ohio 43085 ("Assignor"), and Ehwa Diamond Industrial Co., Ltd., a company organized and existing under the laws of the Republic of Korea, having its principal place of business at 520-2 Wondong, Osansi, Kyunggido, Korea 447804 ("Assignee").

WITNESSETH

WHEREAS, Assignor has developed and owns certain technology related to the Frame Saw and Method, Granite Block and Frame Saw with Support Structure and has filed the Patent Applications thereon, of which some were granted patents and some are still pending, as set forth in Schedule A attached hereto (the "Patents and Patent Applications");

WHEREAS, in accordance with the terms and conditions of this Agreement, Assignor desires to sell, assign, convey and transfer to Assignee all of Assignor's rights, title and interest in the Patents and Patent Applications; and

WHEREAS, Assignee desires to acquire ownership of the Patents and Patent Applications from Assignor.

NOW, THEREFORE, the parties hereto, intending to be legally bound, agree as follows:

Article 1 Assignment

1.1 Assignor hereby sells, assigns, conveys and transfers to Assignee, its successors and assigns, its entire rights, title and interest in and to all of the Patents and Patent Applications, along with its right to sue for past infringement, including all current and future claims and causes of action (the "Assignment").

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Article 7 Termination

7.1 This Agreement shall be effective from the date of execution by both parties ("Effective Date") and shall be effective thereafter unless terminated in accordance with this Agreement.

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APPENDIX A

Family #1 -- FRAME SAW AND METHOD

Granted:

US 7082939 (10/731,066) issued August 1, 2006
US 7089924; issued August 15, 2006
Chinese Application No. 200380105612.7

Pending:

European Patent Application No. 3812902.9; filed December 10, 2003
Indian Patent Application No. 1216/DELNP/2005; filed December 10, 2003
Brazilian Patent Application No. 0316922-7; filed December 10, 2003

Family #2 -- GRANITE BLOCK -

Granted:

US 7096863; issued August 29, 2006

Pending:

Chinese Application No. 20040038738; filed December 22, 2004
European Patent Application No. 4815249.0; filed December 22, 2004
Indian Patent Application No. 3342/DELNP/2006; filed December 24, 2004
Brazilian Patent Application No. PI0417328-7; filed December 22, 2004
South Korean Patent Application No. 10-2006-7012729; filed December 22, 2004

Family #3 -- FRAME SAW WITH SUPPORT STRUCTURE - 12598

Granted:

Indian Patent Application No. 1379/DELNP/2006
Chinese Application No. 200480023359.5
US 7,637,257; issued December 29, 2009
US 7,814,895; issued October 19, 2010

Pending:

US 12/630,887; filed December 4, 2009 -- FRAME SAW WITH SUPPORT
STRUCTURE AND SPACERS; allowed
European Patent Application No. 4781061.9; filed August 13, 2004
Brazilian Patent Application No. PI0413591-1; filed August 13, 2004

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IN WITNESSETH WHEREOF, the Assignor and the Assignee have executed 2 copies of this Agreement, respectively put their names and affixed their seals hereto and shall respectively hold each one copy hereof.

The Assignor

DIAMOND INNOVATIONS INC.

By: 

Name: Mark Schweizer

Title: President

The Assignee

EHWA DIAMOND INDUSTRIAL CO., LTD.

By: 

Name: J. Christine Kim

Title: President

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